



US00D405779S

United States Patent [19]

Huber et al.

[11] Patent Number: **Des. 405,779**

[45] Date of Patent: ****Feb. 16, 1999**

[54] **CARRIER ELEMENT FOR A SEMICONDUCTOR CHIP FOR INTEGRATION INTO A CHIPCARD**

[75] Inventors: **Michael Huber**, Nittendorf; **Peter Stampka**, Schwandorf-Klardorf; **Erik Heinemann**; **Christian Hauser**, both of Regensburg; **Frank Pueschner**, Kelheim, all of Germany

[73] Assignee: **Siemens Aktiengesellschaft**, Munich, Germany

[**] Term: **14 Years**

[21] Appl. No.: **70,054**

[22] Filed: **Apr. 25, 1997**

[30] **Foreign Application Priority Data**

Oct. 25, 1996 [DE] Germany M 96 09 746.9

[51] **LOC (6) Cl.** **14-02**

[52] **U.S. Cl.** **D14/117**

[58] **Field of Search** D14/117, 114; 235/378-390, 492; 361/739, 737-738

[56] **References Cited**

U.S. PATENT DOCUMENTS

D. 342,728	12/1993	Glton	D14/117
D. 344,502	2/1994	Glton	D14/117
D. 353,135	12/1994	Glton	D14/117
D. 353,136	12/1994	Glton	D14/117
D. 365,092	12/1995	Mundigl et al.	D14/117
5,003,520	3/1991	Grieu et al.	235/380 X
5,055,662	10/1991	Hasegawa	235/380 X

Primary Examiner—Brian N. Vinson
Attorney, Agent, or Firm—Herbert L. Lerner; Laurence A. Greenberg

[57] **CLAIM**

The ornamental design for a carrier element for a semiconductor chip for integration into a chipcard, as shown and described.

DESCRIPTION

FIG. 1 is a top, perspective view of a carrier element for a semiconductor chip for integration into a chipcard showing our new design; and, FIG. 2 is a top plan view thereof.

1 Claim, 1 Drawing Sheet

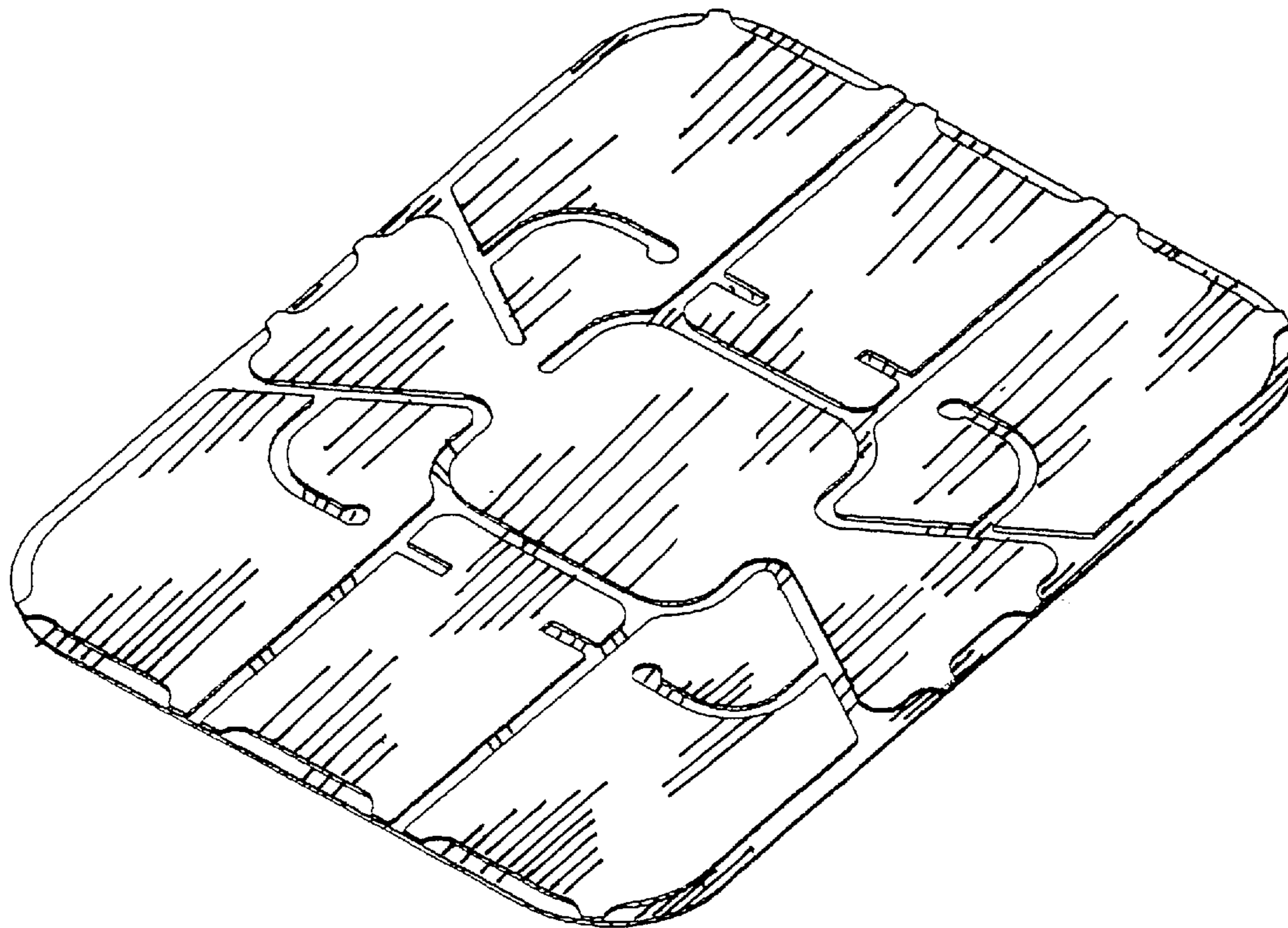


FIG 1

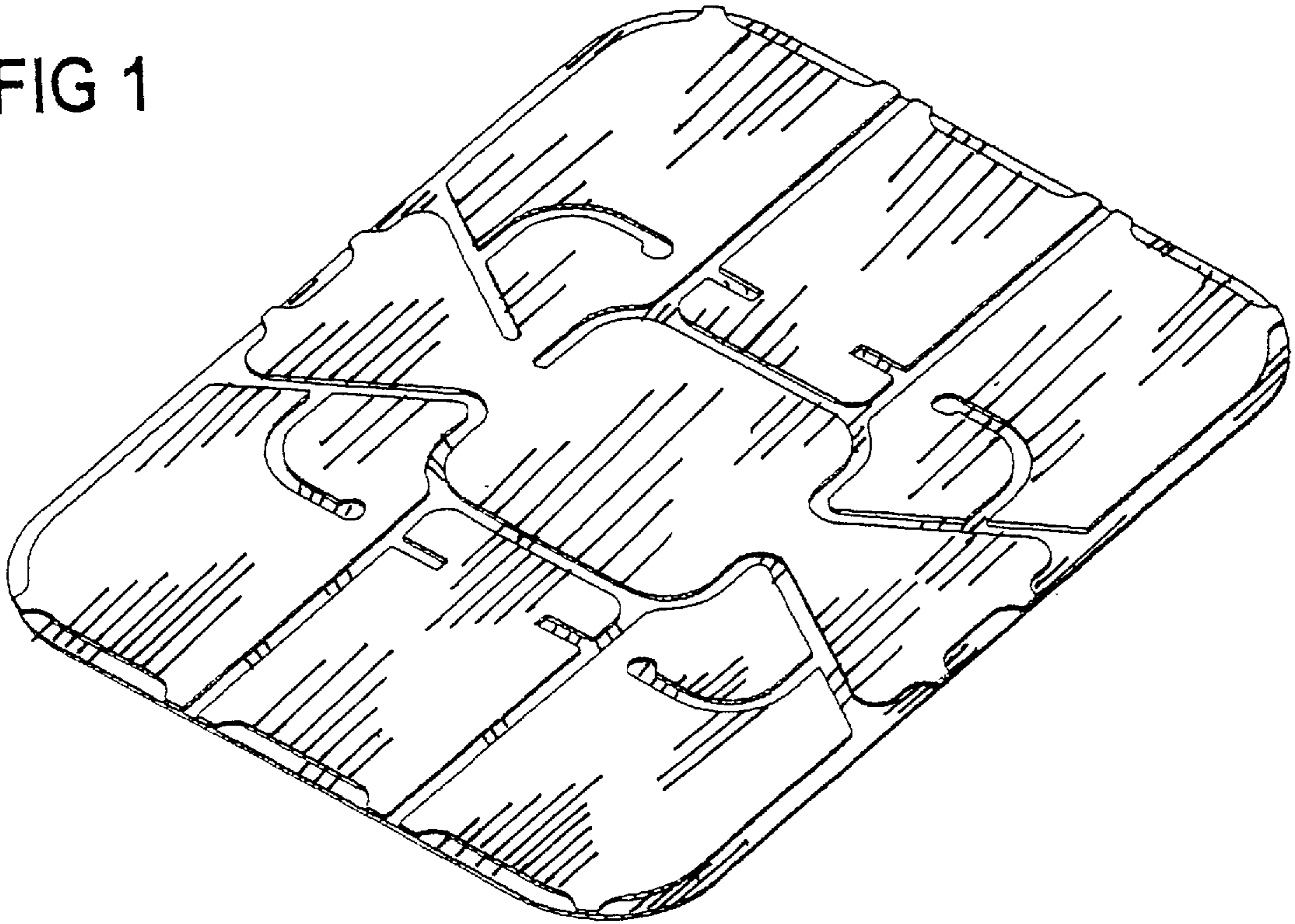


FIG 2

